

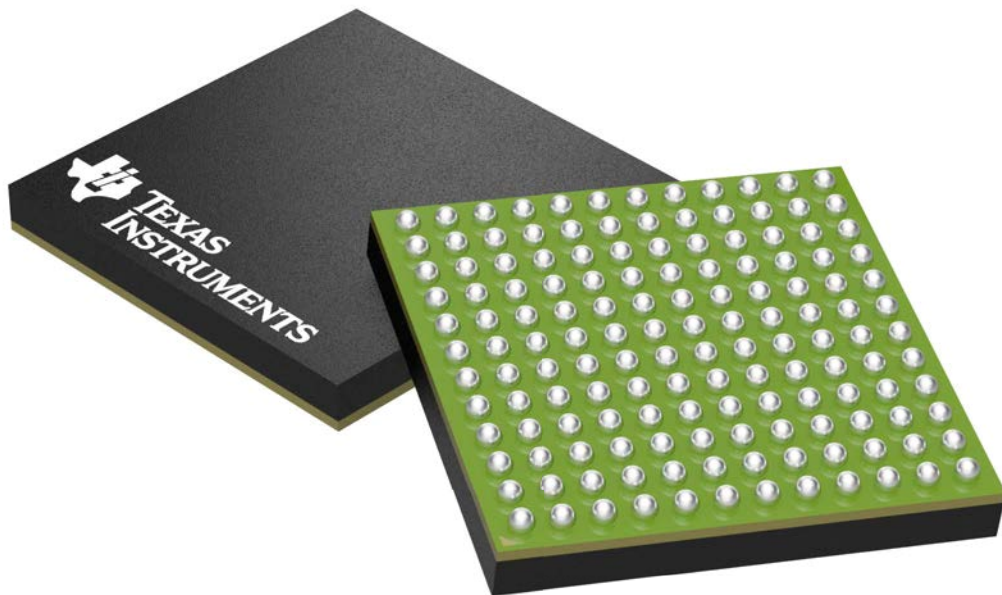
## GENERIC PACKAGE VIEW

**ZCR 144**

**NFBGA - 1.5 mm max height**

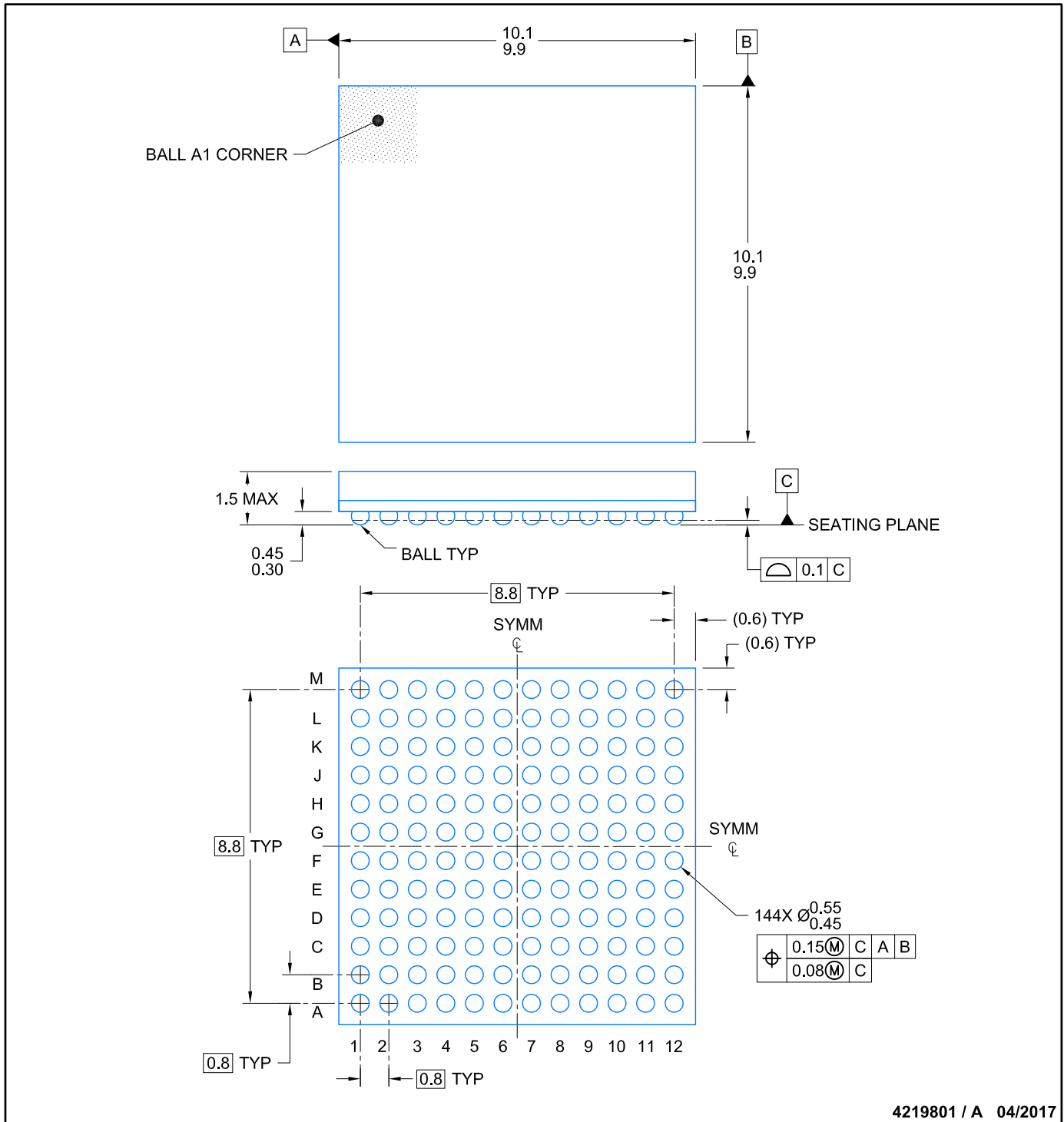
10 x 10 mm, 0.8 mm pitch

PLASTIC BALL GRID ARRAY



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

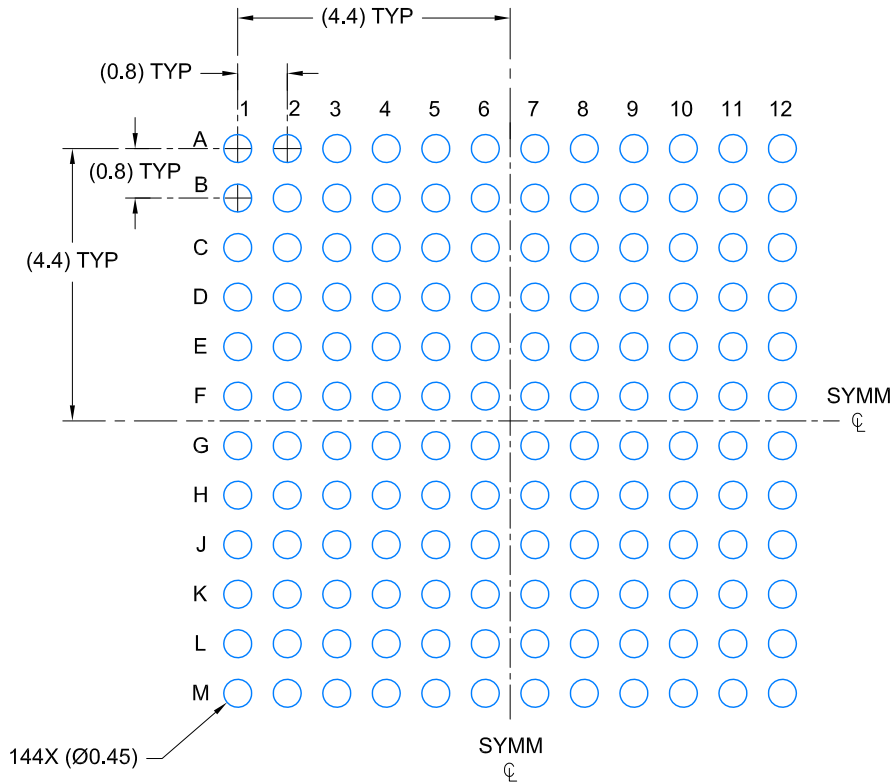
4210272/D



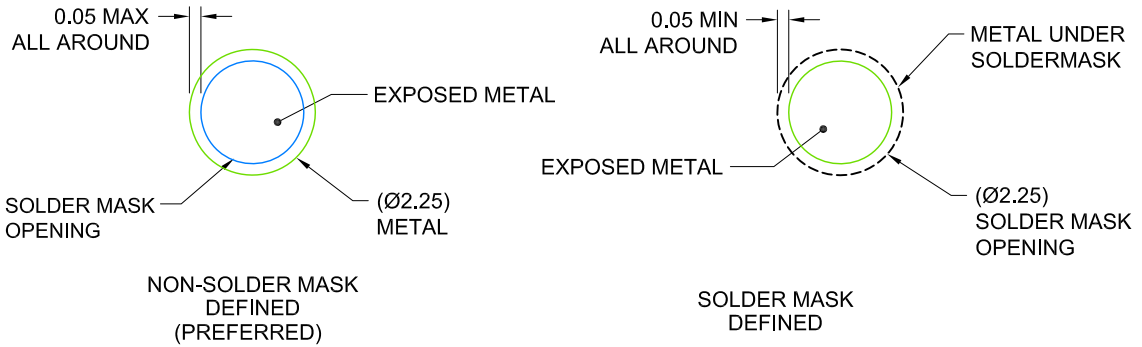
4219801 / A 04/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X

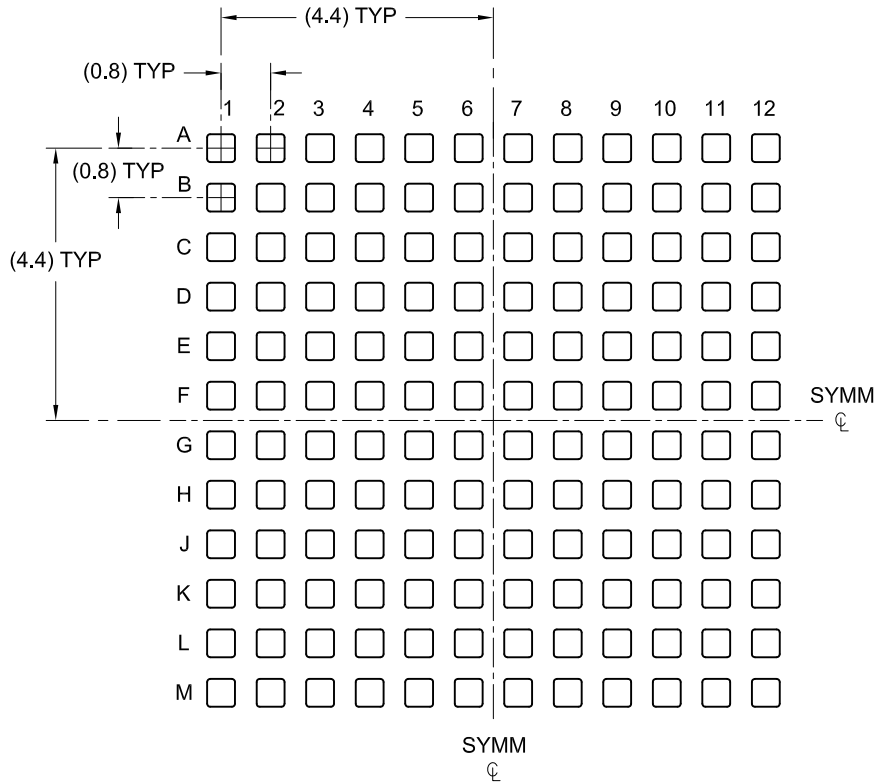


SOLDER MASK DETAILS  
NOT TO SCALE

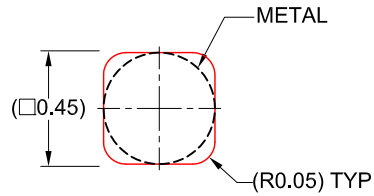
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NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SPRAA99 ([www.ti.com/lit/spraa99](http://www.ti.com/lit/spraa99)).



SOLDER PASTE EXAMPLE  
BASED ON 0.15 mm THICK STENCIL  
SCALE: 8X



DETAIL  
SCALE: 32X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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